	Material Compo © Copyright 2005. IF International and Pan	C, Bannockb	urn, Illinois. A	All rights reserved untions.	under both	This docume level parts, t	ent is a declarat he declaration	ion of the encompass	substances ses all lowe	within the er level mate	manufactur erials for wh	er listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lowe responsibility.	
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	als and Mfg Information				
Supplier	r Information															
Company name* Cor				Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-05-02				
Contact N	lame		Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Version Manufacturing Site		ing Site	V	/eight*	UOM	Unit Type		
		FSGM0565RUDTU Gr		Green Mode FPS			2024-05-02 PE		PBB		2	239.009	mg	Each		
/Ianufa	cturing Proccess Informat	ion										1				
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process Body Temp		Temperatu	ature Max Time at Peak		Temperatu	re Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		C	30		second	s 3					
omments	6															
or more i	information regarding material of	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.8	mg	Supplier	Silicon (Si)	7440-21-3		9.8	mg
Die Attach Epoxy	0.254	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0076	mg
			Supplier	Silver (Ag)	7440-22-4		0.2159	mg
			Supplier	Proprietary	Proprietary Data		0.0127	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0178	mg
vie Attach Solder	3.061	mg	Supplier	Silver (Ag)	7440-22-4		0.0765	mg
			А	Lead (Pb)	7439-92-1	7a	2.8314	mg
			Supplier	Tin (Sn)	7440-31-5		0.1531	mg
lead Frame	1264.59	mg	Supplier	Silver (Ag)	7440-22-4		2.91	mg
			Supplier	Tin (Sn)	7440-31-5		1.55	mg
			Supplier	Copper (Cu)	7440-50-8		1260.0045	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1255	mg
Iold Compound-Black	950.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		114	mg
			Supplier	Carbon Black (C)	1333-86-4		4.75	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		831.25	mg
Plating	11.0	mg	Supplier	Tin (Sn)	7440-31-5		11	mg
Wire Bond - Cu	0.304	mg	Supplier	Copper (Cu)	7440-50-8		0.304	mg